

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>DUCK HWAN KIM</td> <td>12/02/2013</td> </tr> <tr> <td>IN SANG SONG</td> <td>12/02/2013</td> </tr> <tr> <td>JEA SHIK SHIN</td> <td>12/02/2013</td> </tr> <tr> <td>HO SOO PARK</td> <td>12/02/2013</td> </tr> <tr> <td>JAE-SUNG RIEH</td> <td>12/02/2013</td> </tr> <tr> <td>BYEONG KWON JU</td> <td>12/02/2013</td> </tr> </tbody> </table>		Name	Execution Date	DUCK HWAN KIM	12/02/2013	IN SANG SONG	12/02/2013	JEA SHIK SHIN	12/02/2013	HO SOO PARK	12/02/2013	JAE-SUNG RIEH	12/02/2013	BYEONG KWON JU	12/02/2013
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<table border="1"> <tr> <td>Name:</td> <td>SAMSUNG ELECTRONICS CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>129, SAMSUNG-RO, YEONGTONG-GU, SUWON-SI, GYEONGGI-DO, 443-742</td> </tr> <tr> <td>City:</td> <td>SUWON-SI</td> </tr> <tr> <td>State/Country:</td> <td>KOREA, REPUBLIC OF</td> </tr> </table>		Name:	SAMSUNG ELECTRONICS CO., LTD.	Street Address:	129, SAMSUNG-RO, YEONGTONG-GU, SUWON-SI, GYEONGGI-DO, 443-742	City:	SUWON-SI	State/Country:	KOREA, REPUBLIC OF						
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PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14094178</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14094178										
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Application Number:	14094178														
CORRESPONDENCE DATA															
Fax Number:	(202)315-3758														
Phone:	2024290020														
Email:	pto@nsiplaw.com														
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
Correspondent Name:	NSIP LAW														
Address Line 1:	P.O. BOX 65745														

Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20035	
NAME OF SUBMITTER:	LOREN H. TUNG
Signature:	/Loren H. Tung/
Date:	01/02/2014
Total Attachments: 3 source=NewApp_0120520675_CDAAExecuted_asfiled#page1.tif source=NewApp_0120520675_CDAAExecuted_asfiled#page2.tif source=NewApp_0120520675_CDAAExecuted_asfiled#page3.tif	

COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

DECLARATION

As a below-named inventor, I hereby declare that this declaration is directed to the application attached hereto, or to United States Application Number or PCT International Application Number 14/094,178 filed on December 2, 2013 (if applicable), entitled:

APPARATUS AND METHOD FOR FABRICATING NANO RESONATOR USING LASER INTERFERENCE LITHOGRAPHY

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information that became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

ASSIGNMENT

For valuable consideration, I, as a below-named assignor, hereby assign to:

SAMSUNG ELECTRONICS CO., LTD.
129, Samsung-ro, Yeongtong-gu
Suwon-si, Gyeonggi-do 443-742
Republic of Korea

Korea University Industrial & Academic Collaboration Foundation
Korea Univ., Anam-dong 5(o)-ga, Seongbuk-gu
Seoul 136-701
Republic of Korea

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title, and interest throughout the world in the inventions and improvements that are the subject of the application identified in the above declaration, which is United States Application Number or PCT International Application Number 14/094,178 filed on December 2, 2013.

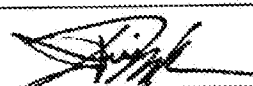
I authorize and request the attorneys appointed in the above-identified application to hereafter complete this Assignment by inserting above the application number and the filing date of the above-identified application when known, and to correct any typographical errors that may be discovered in this Assignment.

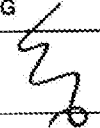
This Assignment includes the above-identified application, any and all United States and foreign patents, utility models, and design registrations granted for any of the inventions and improvements that are the subject of the above-identified application, and the right to claim priority based on the filing date of the above-identified


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application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations, like rights of exclusion, and inventors' certificates for any of the inventions and improvements that are the subject of the above-identified application; and I agree for myself and my heirs, legal representatives, and assigns without further compensation to perform such lawful acts and to sign such further applications, Assignments, preliminary statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

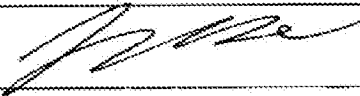
In witness whereof, I, as a below-named inventor and assignor, intending to be legally bound, have hereunto affixed my signature on the date indicated below next to my signature.

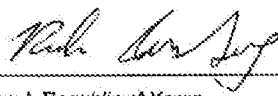
Inventor's Legal Name	Duck Hwan KIM		
Inventor's Signature		Date	12 / 02 / 2013
Residence (City, Country)	Goyang-si, Republic of Korea		
Mailing Address	Samsung Advanced Institute of Technology, Mt. 14-1, Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do 446-712, Republic of Korea		

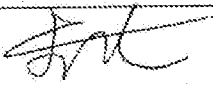
Inventor's Legal Name	In Sang SONG		
Inventor's Signature		Date	12 / 02 / 2013
Residence (City, Country)	Osan-si, Republic of Korea		
Mailing Address	Samsung Advanced Institute of Technology, Mt. 14-1, Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do 446-712, Republic of Korea		

Inventor's Legal Name	Jea Shik SHIN		
Inventor's Signature		Date	12 / 02 / 2013
Residence (City, Country)	Hwaseong-si, Republic of Korea		
Mailing Address	Samsung Advanced Institute of Technology, Mt. 14-1, Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do 446-712, Republic of Korea		

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Inventor's Legal Name	Ho Soo PARK		
Inventor's Signature		Date	12 / 02 / 2013
Residence (City, Country)	Yongin-si, Republic of Korea		
Mailing Address	Samsung Advanced Institute of Technology, Mt. 14-1, Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do 446-712, Republic of Korea		

Inventor's Legal Name	Jae-Sung RIEH		
Inventor's Signature		Date	12 / 02 / 2013
Residence (City, Country)	Seoul, Republic of Korea		
Mailing Address	Korea University Industrial & Academic Collaboration Foundation, Korea Univ., Anam-dong 5(o)-ga, Seongbuk-gu, Seoul 136-701, Republic of Korea		

Inventor's Legal Name	Byeong Kwon JU		
Inventor's Signature		Date	12 / 02 / 2013
Residence (City, Country)	Seoul, Republic of Korea		
Mailing Address	Korea University Industrial & Academic Collaboration Foundation, Korea Univ., Anam-dong 5(o)-ga, Seongbuk-gu, Seoul 136-701, Republic of Korea		